



Koh Young Shares Revolutionary Advanced Package Inspection Solutions at the SMTA Wafer-Level Packaging Symposium in Burlingame, CA on 12 February 2024

Atlanta, Georgia – Koh Young Technology, the leader in True3D™ measurement-based inspection solutions, will be speaking at the SMTA Wafer-Level Packaging Symposium in Burlingame, California on our Multimodal Phase Shift Optics Approach to revolutionize high-speed 3D reconstruction of semiconductor and advanced packages. In the presentation will highlight how high-speed 3D reconstruction addresses the growing demand for electronic components, which necessitates fast and efficient processing. These advancements in measurement technology and AI integration have paved the way for enhanced packaging applications in the semiconductor industry.

During the event on Tuesday, 13 February 2024, Dr. Seung Hyun Lee, Ph.D. will present the paper "*High-Speed Die and Component 3D Reconstruction Solution by Multimodal Phase Shift Optics Approach*". Therein he will explain how advancements in optical 3D measurement and the integration of Artificial Intelligence (AI) have paved the way for advanced packaging applications. Multi-modal measurement probes, equipped with enhanced depth of focus, can cover height differences in the latest package designs. Various surface conditions of components, chips, and surfaces are measured by combining an oblique optical system, which ensures stable high-speed measurement of objects with diffuse reflection, with a coaxial optical system, suitable for measuring objects with specular reflection. The integration of AI deep learning technology enables effective processing of various noises encountered during the measurements.



The SMTA WLPS will explore the massive changes in advanced package technology because electrical system architects are directly driving package performance requirements, something which has never happened before. Previously System Architects designed circuits around package limitations because pushing package technologies outside of their "comfort zones" often led to undesirable results. With the rise in transistor costs and the need to improve power efficiency, Silicon Architects have little choice but to push advanced package technologies well beyond their comfort zones.

The Wafer-Level Packaging Symposium will bring together the semiconductor industry's most respected authorities to address all aspects of wafer-level, 3D device packaging, advanced manufacturing & test technologies. Addressing wafer-level packaging, 3D, and Advanced Manufacturing & Test technologies, the Wafer-Level Packaging Symposium will be at the forefront of packaging technology evolution. The conference will feature attendees from around the globe in the heart of Silicon Valley to immerse themselves in the latest technology and business trends. Register today at www.smta.org/mpage/wafer-register.





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About Koh Young Technology, Inc.

Established in 2002, Koh Young revolutionized the inspection market by launching the industry's first 3D Solder Paste Inspection (SPI) system using a patented dual-projection Moiré technology. Since then, it has become the global leader in 3D measurement-based SPI and Automated Optical Inspection (AOI) equipment for the electronics industry. Based on its True3D™ measurement-based inspection technology, Koh Young has developed innovative inspection solutions for challenges with machined parts, press-fit and through-hole pins, conformal coatings, dispensed materials, and semiconductor packages. Through its constant innovation, Koh Young has secured over 3,500 global customers, and commands the dominant global market share position in the SPI and AOI markets with well over 20,000 machine installations. A customer-centric R&D focus uses our core competencies to develop innovative solutions for new and existing markets by listening to users and researching trends and applications. From the headquarters in Korea, activities spread across the world through its global sales and support infrastructure spanning Europe, Asia, and the Americas. These regional offices ensure Koh Young stays close to the market, and more importantly, its growing user base. Learn why so many electronics manufacturers trust Koh Young for reliable inspection for a smart factory at our website at www.kohyoungamerica.com.

For More Information

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